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REMARKS

Careful consideration has been given by the applicants to the Examiner's comments and rejection of the claims, as set forth in the outstanding Office Action, and favorable reconsideration and allowance of the application, as amended herein, is earnestly solicited.

Applicants note that the Examiner's reiterates the citation of Japanese Patent Publication JP 11-107,112 in rejecting Claims 13 and 14 under 35 U.S. C. §103(a) as being unpatentable, as detailed in Paragraph 4 of the Office Action.

Concerning the foregoing, applicants note that the Examiner is of the opinion that this Japanese publication teaches optimizing weave density by making the spacing between the adjacent strands as small as possible to increase the accuracy and efficiency of circuit boards which employ the fiberglass cloths.

However, although the Examiner indicates that this is a result effective variable, in essence, the rejection is based on a citation or setting forth of a problem, rather than a solution, which is offered by the present applicants, contrary to the teachings of the Japanese publication.

In essence, it is an imperative in the present invention to optimize the structure of the laminate support in a wire-bonded circuit device in a manner that will prevent the collapse or damage to be incurred by a circuit pad arranged on a substrate. However, it remained for the present applicants to provide specific parameters which enable the structure of the laminate support in a highly efficient and economical mode providing for the desired results.

To the contrary, the Japanese publication, although concerned with woven cloths and supports on a circuit board, fails to provide the particular parameters which are afforded by the present invention, but rather generally sets forth the intent providing an optimization. This intent of optimization is also provided for by the present invention, but contrary to the Japanese publication in a completely different manner in specifying the specific separation distances as being within about 0.2 to 0.7 mils between strands and wherein the substrate has a thickness of between about 2.5 to 4.0 mils. This is an optimized size for the particular application of the wire-bonded circuit devices employing these structures. To the contrary, as previously indicated, the Japanese publication provides for parameters and sizes completely outside the scope and limitations defined for by the present invention.

Concerning the foregoing, applicants reiterate the arguments submitted in traverse of the Japanese publication in response to the previous Office Action and as also submitted in the remarks filed in the Preliminary Amendment in this application on April 4, 2006.

As indicated previously, the particular dimensional aspects provided for by the present invention, as set forth in the claims presented herewith and as also previously submitted, provide an accurate and precise optimization of the type of laminate support for the wire bonded circuit device at a minimum amount of weight and physical displacement. The Japanese publication in no manner provides any optimized values analogous to those presented and claimed herein, but provides for a general discussion and completely different physical parameters, which cannot be utilized in conjunction with the type of structure considered by the present invention.

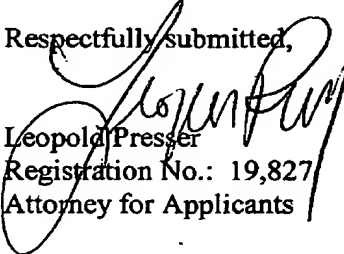
It remained for the present applicants to provide for the optimized values, which are clearly disclosed and claimed herein in order to obtain the desired physical aspects for the laminate support and which in no manner is considered to be disclosed nor rendered obvious from the disclosure of the cited Japanese publication or any other art which has been cited or which is known to the applicants.

In summation, again reiterating applicants position and arguments, the present claims are clearly and patentably distinct over the cited Japanese publication setting forth the particular parameters and optimized values, which are specifically utilized in a particular laminate support, as described and claimed herein.

In view of the foregoing comments and amendments, which are deemed to be fully responsive to the Examiner's rejection of the claims and which are clearly distinct in a patentable mode over the art, the early and favorable reconsideration and allowance of the application by the Examiner is earnestly solicited:

However, in the event that the Examiner has any queries concerning the instantly submitted Amendment, applicants' attorney respectfully requests that he be accorded the courtesy of possibly a telephone conference to discuss any matters in need of attention.

Respectfully submitted,

  
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